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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Shih-Kuang CHIU

*MRD
7.31.00*

Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):

Name: Siliconware Precision Industries Co., Ltd.

Address: _____

No. 123, Sec. 3, Da Fong Road, Tantz

City: Taichung, State/Prov.: _____

Country: Taiwan, R.O.C. ZIP: _____

Additional name(s) & address(es) Yes No



3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: April 28, 2000

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 04/28/00

Patent Application No. _____ Filing date _____

B. Patent No.(s) _____

09/629068

Additional numbers

Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Peter F. Corless

Registration No. 33,860

Address: EDWARDS & ANGELL, LLP

Dike, Bronstein, Roberts & Cushman, IP Group

130 Water Street

City: Boston State/Prov.: MA

Country: U.S.A. ZIP: 02109

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

Authorized to be charged to deposit account

8. Deposit account number:

04-1105

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless

Name of Person Signing

[Signature]

Signature

July 28, 2000

Date

Total number of pages including cover sheet, attachments, and

2

PATENT

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

*Inventor(s)
Full Name(s)*

Shih-Kuang Chiu
.....
.....

*Assignee
Name and
Address*

hereby sell, assign and transfer to
SILICONWARE PRECISION INDUSTRIES CO., LTD.
No. 123, Sec. 3, Da Fong Road, Tantzsu, Taichung, Taiwan, R.O.C.
.....

*Title of
Invention*

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled
"SEMICONDUCTOR PACKAGE STRUCTURE WITH A HEAT-DISSIPATION STIFFENER AND METHOD OF FABRICATING THE SAME"
.....

*Complete
either
a) or b)*

which application was
a) executed by the undersigned on the day of, 19
b) filed on the day of, 19

Serial No
including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date

Signed at Taichung, Taiwan, R.O.C.
this 28 day of April, 19 2000.

*Inventor(s)
Full
Signature(s)*

INVENTOR(S):
Shih Kuang Chiu (Shih-Kuang Chiu)
.....
.....

*Witnesses'
Full
Signatures*

WITNESSES:
.....
.....